

ASSIGNMENT RECO

09-25-2003

Patents Only



To the Honorable Commiss.

102558751

Date: September 16, 2003
Attorney Docket No. 5649.1161

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

9.16.03

Hyun-Chul Kim

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.
416 Maetan-dong, Paldal-gu
Suwon-city, Kyungki-do
Republic of Korea

Additional name(s) of conveying party(ies) attached? Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Other

Execution Date: September 7, 2003

Additional name(s) & address(es) attached? Yes ☒ No

4. Application Serial No. _____ Patent No. _____

10663967

If this document is being filed together with a new application, the execution date of the application is: September 12, 2003

Additional numbers attached? Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Elizabeth A. Stanek
Myers Bigel Sibley & Sajovec
P. O. Box 37428
Raleigh NC 27627

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00
☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number: 50-0220

DO NOT USE THIS SPACE

9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Elizabeth A. Stanek Reg # 48,568

Elizabeth A. Stanek

September 16, 2003

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and document: 3

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PATENT
REEL: 014509 FRAME: 0099

ASSIGNMENT

THIS ASSIGNMENT, made by me, **Hyun-Chul Kim**, 9-601 Misung Apt., 17-6
Shincheon-dong, Songpa-gu, Seoul-city, Republic of Korea;

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in
**INTEGRATED CIRCUIT DEVICES HAVING FUSE STRUCTURES INCLUDING
BUFFER LAYERS AND METHODS OF FABRICATING THE SAME** for which an
application for United States Letters Patent has been filed, or is being filed concurrently, in the
United States Patent and Trademark Office. I hereby authorize and request Myers Bigel Sibley
& Sajovec, P.A., to insert here in parentheses (Application No. _____ filed
_____) the application number and filing date of said application when known or to
file this Assignment concurrently with the application, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal
place of business at 416 Maetan-dong, Paldal-ku, Suwon-city, Kyungki-do, Republic of Korea,
hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in
and to said invention as described in said application, and in and to any and all Letters Patent
which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable
consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by
these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors
and assigns, the entire right, title and interest in and to the said invention and application, and in
and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any
and all Letters Patent of the United States of America and all foreign countries or reissues
thereof which may be granted therefor or thereon, for the full end of the term for which said
Letters Patent may be granted, together with the right to claim the priority of said application in
all foreign countries in accordance with the International Convention, the same to be held and
enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would
have been held and enjoyed by me if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment. I
further covenant and agree that, at the time of the execution and delivery of these presents, I
possess full title to the invention and application above-mentioned, and that I have the
unencumbered right and authority to make this assignment.

I further covenant and agree to bind my heirs, legal representatives and assigns, promptly
to communicate to said assignee or its representatives any facts known to me relating to said
invention, to testify in any interference or legal proceedings involving said invention, to execute

any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this _____ day of 3th, Sep., 2003.

Hyun-Chul Kim (SEAL)
Hyun-Chul Kim

Witnessed by:

Date: _____

Date: _____